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**EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE****Publication Number:** 2001-226561 (JP 2001226561 A), August 21, 2001**Inventors:**

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**Application Number:** 11-353024 (JP 99353024), December 13, 1999**Priority:**

- 11-349634 [JP 99349634], JP (Japan), December 09, 1999

**International Class:**

- C08L-063/00
- C08K-003/22
- H01L-023/29
- H01L-023/31

**Abstract:**

**PROBLEM TO BE SOLVED:** To obtain an epoxy resin composition for sealing a semiconductor which does not contain a halogen-containing flame-retardant and an antimony compound and is excellent in molding properties, flame retardancy, high temperature storage characteristics, moisture resistance reliability and solder crack resistance. **SOLUTION:** The epoxy resin composition for sealing a semiconductor comprises, as essential ingredients, (A) an epoxy resin, (B) a phenolic resin, (C) a curing accelerator, (D) an inorganic filler and (E) a metal hydroxide solid solution represented by the general formula:  $Mg_{1-x}M_2^{2+}x(OH)_2$  (wherein  $M_2^{2+}$  is at least one divalent metal ion selected from the group consisting of  $Mn^{2+}$ ,  $Fe^{2+}$ ,  $Co^{2+}$ ,  $Ni^{2+}$ ,  $Cu^{2+}$  and  $Zn^{2+}$ ; and (x) is a number of  $0.01 \leq x \leq 0.5$ ), and the specific surface area of the metal hydroxide solid solution represented by the general formula is  $1.5\text{--}4.5\text{ m}^2/\text{g}$ . **COPYRIGHT:** (C)2001,JPO

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Dialog® File Number 347 Accession Number 6998961